



# ALLIANCE MEMORY MDS REPORT

Package Material Declaration Sheet (MDS)										
AS7C4096A-xxJCN/JIN										
	Package type:	36pin SOJ 400 mil		Date:	3/23/2014			Approved	Prepared	
	Package weight (mg):	1458.195		Company Name:	Alliance Memory Inc.			Dick	Ram	
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt (%)	Element (mg)	Wt % Of Total Unit Wt	ppm	
1	Leadframe (ROKKO)	C194	273.0068	Copper (Cu)	7440-50-8	96.26%	262.79	18.02%	180216	
				Fe	7439-89-6	2.35%	6.42	0.44%	4400	
				Zinc	7440-66-6	0.08%	0.23	0.02%	154	
				Phosphorus (P)	7723-14-0	0.03%	0.08	0.01%	56	
				Pb	7439-92-1	0.03%	0.00	0.01%	56	
				Ag	7440-22-4	1.25%	0.03	0.23%	23	
								0.00	0.00%	0
								0.00	0.00%	0
2	Die attach material Hitachi Epoxy	EN-4900G*	1.2435	Acrylic resin	Trade Secret	8.00%	0.10	0.01%	68	
				Polybutadiene derivative	Trade Secret	5.00%	0.06	0.00%	43	
				Butadiene copolymer	Trade Secret	2.00%	0.02	0.00%	17	
				Epoxy resin	Trade Secret	2.00%	0.02	0.00%	17	
				Acrylate	Trade Secret	4.00%	0.05	0.00%	34	
				Peroxide	Trade Secret	1.00%	0.01	0.00%	9	
				Additive	Trade Secret	2.00%	0.02	0.00%	17	
	Silver	7440-22-4	76.00%	0.95	0.06%	648				
3	Gold Wire Heesung	Gold	1.0437	Au	7440-57-5	100.00%	1.04	0.07%	716	
4	Tin Plate (Redsun)	Pure Tin	15.6234	Sn	7440-31-5	100.00%	15.62	1.07%	10714	
5	Mold Compound Hitachi 9240HF	CEL-9240HF	1133.1890	Epoxy resin-1	Trade secret	4.50%	50.99	3.50%	34970	
				Epoxy resin2	Trade secret	1.00%	11.33	0.78%	7771	
				Hardener 1	Trade secret	4.50%	50.99	3.50%	34970	
				Hardener 2	Trade secret	4.50%	50.99	3.50%	34970	
				CarbonBlack	1333-86-4	0.20%	2.27	0.16%	1554	
				Amorphous Silica	60676-86-0	82.80%	938.28	64.35%	643453	
	Crystal Silica	14808-60-7	2.50%	28.33	1.94%	19428				
6	Die	Silicon Chip	34.0889	Si	-	100.00%	34.09	2.34%	23377	
Total unit weight =			1458.195							

Note:

- (A) Element Wt Composition is derived from MSDS and/or material C of C from Vendors
- (B) Wt of silver spotted on leadframe is estimated.
- (C) Component Weight based on assembly of generic parts.